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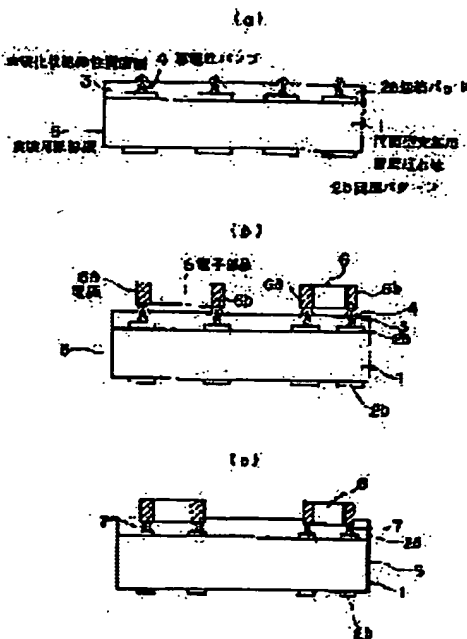
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(54) WIRING BOARD AND MOUNTING METHOD USING IT

(57)Abstract:

PURPOSE: To obtain a circuit device of high reliability at low cost by covering with an unhardened insulating resin layer at least part of a surface of a wiring board for mounting equipped with a group of conductive bumps, which has a connection pad group, each equipped with a conductive bump.

CONSTITUTION: A chip mounter is used for a conductive bump 4 of a wiring board 5 for mounting to match, position and arrange electrodes 6a and 6b of a chip-shape resistant element. For this positioning arrangement, a weight is applied instantaneously to the chip mounter to make the tip of the conductive bump 4 in a crushed shape, thus reducing the conductive bump 4 height. Next, this is left in room temperature to harden a room-temperature hardening type silicone resin as an unhardened-shape insulating resin layer 3. This enables the unhardened insulating resin layer 3 to isolate and insulate each connecting part. On the other hand, once it is hardened, its connecting parts are protected from the outer surface and making packaged electronic parts and the wiring board into one unit and fixing it are promoted, thus obtaining the packaged circuit device of high reliability.



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